

PMP8750\_RevB\_3 BOM

Designator	Quantity	Value	Description	PackageReference	PartNumber	Manufacturer
C301	1	2200pF	CAP, CERM, 2200pF, 50V, +/-10%, X7R, 0603	0603	C0603C222K5RACTU	Kemet
C302, C303	3	DNP		0805		MuRata
C304	3	10uF	CAP, CERM, 10uF, 10V, +/-10%, X7R, 0805	0805	GRM21BR71A106KE51L	MuRata
C305, C311	2	0.1uF	CAP, CERM, 0.1uF, 50V, +/-10%, X7R, 0603	0603	06035C104KAT2A	AVX
C306, C307, C308, C309, C310	5	22uF	CAP, CERM, 22uF, 10V, +/-20%, X5R, 1210	1210	C3225X5R1A226M	TDK
C312	1	DNP	CAP, CERM, 10pF, 50V, +/-5%, C0G/NP0, 0603	0603	06035A100JAT2A	AVX
C313	1	10pF	CAP, CERM, 10pF, 50V, +/-5%, C0G/NP0, 0603	0603	06035A100JAT2A	AVX
C314, C315	2	0.01uF	CAP, CERM, 0.01uF, 50V, +/-10%, X7R, 0603	0603	GRM188R71H103KA01D	MuRata
J301, J302	2		Terminal Block, 6A, 3.5mm Pitch, 2-Pos, TH	7.0x8.2x6.5mm	ED555/2DS	On-Shore Technology
L301	1	1.5uH	Inductor, Shielded, Composite, 1.5uH, 6.6A, 0.0162 ohm, SMD	7.5x1.5x7.5 mm	XFL7015-152MEB	Coilcraft
R301	1	4.7	RES, 4.7 ohm, 5%, 0.125W, 0805	0805	CRCW08054R70JNEA	Vishay-Dale
R302	1	49.9	RES, 49.9 ohm, 1%, 0.1W, 0603	0603	CRCW060349R9FKEA	Vishay-Dale
R303	1	56.2k	RES, 56.2k ohm, 1%, 0.1W, 0603	0603	CRCW060356K2FKEA	Vishay-Dale
R305	1	49.9k	RES, 49.9k ohm, 1%, 0.1W, 0603	0603	CRCW060349K9FKEA	Vishay-Dale
R306	1	100k	RES, 100k ohm, 1%, 0.1W, 0603	0603	CRCW0603100KFKEA	Vishay-Dale
R307	1	15.4k	RES, 15.4k ohm, 1%, 0.1W, 0603	0603	CRCW060315K4FKEA	Vishay-Dale
R308	1	13.7k	RES, 13.7k ohm, 1%, 0.1W, 0603	0603	CRCW060313K7FKEA	Vishay-Dale
R309	1	90.9k	RES, 90.9k ohm, 1%, 0.1W, 0603	0603	CRCW060390K9FKEA	Vishay-Dale
R320	1	20.0k	RES, 20.0k ohm, 1%, 0.1W, 0603	0603	CRCW060320K0FKEA	Vishay-Dale
TP303, TP305, TP306	3	Red	Test Point, Miniature, Red, TH	Red Miniature Testpoint	5000	Keystone
TP304	1	Black	Test Point, Miniature, Black, TH	Black Miniature Testpoint	5001	Keystone
U301	1	TPS57114Q1	IC, DC-DC Converter, xxV xx V, xA	WQFN	TPS57114QRTE	TI

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